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ABSTRACT

A high frequency circuit includes a first insulating layer; a second insulating layer stacked on the first insulating layer directly or with one or more intermediate layers interposed therebetween; a first ground disposed on a first surface that does not face the second insulating layer among the first surface and a second surface forming two surfaces of the first insulating layer; a first line having a first end portion to which a first alternating-current signal is to be supplied and a second line having a second end portion to which a second alternating-current signal is to be supplied that are disposed between the first insulating layer and the second insulating layer; a second ground disposed on a third surface that does not face the first insulating layer among the third surface and a fourth surface forming two surfaces of the second insulating layer; and a first shield via.

